

# INTERNATIONAL STANDARD

## NORME INTERNATIONALE

**Field Device Integration (FDI)<sup>®</sup> –  
Part 101-2: Profiles – Foundation Fieldbus HSE**

**Intégration des appareils de terrain (FDI)<sup>®</sup> –  
Partie 101-2: Profils – Foundation Fieldbus HSE**



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## CONTENTS

FOREWORD.....	4
1 Scope.....	6
2 Normative references .....	6
3 Terms, definitions, abbreviated terms and acronyms .....	7
3.1 Terms and definitions.....	7
3.2 Abbreviated terms and acronyms .....	7
4 Conventions .....	7
4.1 EDDL syntax.....	7
4.2 XML syntax.....	7
5 Profile for CP 1/2 (FOUNDATION™ HSE) .....	8
5.1 General.....	8
5.2 Catalog profile .....	8
5.2.1 Protocol support file (Capability File) .....	8
5.2.2 CommunicationProfile definition.....	8
5.2.3 Profile device.....	8
5.2.4 Protocol version information .....	8
5.3 Associating a Package with a CP 1/2 device .....	9
5.3.1 Device type identification mapping.....	9
5.3.2 Device type revision mapping .....	9
5.4 Information Model mapping.....	9
5.4.1 ProtocolType definition .....	9
5.4.2 DeviceType mapping .....	9
5.4.3 FunctionalGroup Identification definition .....	10
5.4.4 BlockType property mapping .....	10
5.4.5 Mapping to Block Parameter Set.....	11
5.5 Topology elements.....	11
5.5.1 ConnectionPoint definition .....	11
5.5.2 Communication Device definition .....	12
5.5.3 Communication service provider definition .....	14
5.5.4 Network definition .....	14
5.6 Methods.....	15
5.6.1 Methods for FDI® Communication Servers .....	15
5.6.2 Methods for Gateways .....	21
Annex A (normative) Topology scan schema.....	22
A.1 General.....	22
A.2 Target Namespace.....	22
A.3 Network .....	22
A.4 FoundationHSEAddressT .....	22
A.5 FoundationHSEConnectionPointT .....	22
A.6 FoundationHSENetworkT .....	23
A.7 FoundationBlockIdentificationT .....	24
A.8 FoundationIdentificationT .....	24
Annex B (normative) Transfer service parameters.....	26
Annex C (informative) Communication service arguments for Transfer Method .....	27
Bibliography.....	28

Table 1 – Capability File part .....	8
Table 2 – CommunicationProfile definition .....	8
Table 3 – Device type catalog mapping .....	9
Table 4 – ProtocolType Foundation_HSE definition .....	9
Table 5 – Inherited DeviceType property mapping .....	10
Table 6 – Identification parameters .....	10
Table 7 – Inherited BlockType property mapping .....	11
Table 8 – ConnectionPointType ConnectionPoint_Foundation_HSE definition .....	11
Table 9 – Communication device ParameterSet definition .....	14
Table 10 – Method Connect arguments .....	16
Table 11 – Method Disconnect arguments .....	16
Table 12 – Method Transfer arguments .....	17
Table 13 – Method GetPublishedData arguments .....	19
Table 14 – Method SetAddress arguments .....	20
Table A.1 – Attributes of FoundationHSEConnectionPointT .....	23
Table A.2 – Elements of FoundationHSEConnectionPointT .....	23
Table A.3 – Elements of FoundationHSENetworkT .....	24
Table A.4 – Attributes of FoundationBlockIdentificationT .....	24
Table A.5 – Attributes of FoundationIdentificationT .....	25

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## FIELD DEVICE INTEGRATION (FDI®) –

## Part 101-2: Profiles – Foundation Fieldbus HSE

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IEC 62769-101-2 has been prepared by subcommittee 65E: Devices and integration in enterprise systems, of IEC technical committee 65: Industrial-process measurement, control and automation. It is an International Standard.

This third edition cancels and replaces the second edition published in 2020. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) added namespace to Annex A;
- b) changed content type of cff file to application/vnd.ff.cff.

The text of this International Standard is based on the following documents:

Draft	Report on voting
65E/861/CDV	65E/918/RVC

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at [www.iec.ch/members\\_experts/refdocs](http://www.iec.ch/members_experts/refdocs). The main document types developed by IEC are described in greater detail at [www.iec.ch/standardsdev/publications](http://www.iec.ch/standardsdev/publications).

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## FIELD DEVICE INTEGRATION (FDI®) –

### Part 101-2: Profiles – Foundation Fieldbus HSE

#### 1 Scope

This part of IEC 62769 specifies the IEC 62769 profile for IEC 61784-1, CP 1/2 (FOUNDATION™ Fieldbus HSE)<sup>1</sup>.

#### 2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 61784-1, *Industrial communication networks – Profiles – Part 1: Fieldbus Profiles*

IEC 61784-2, *Industrial communication networks – Profiles – Part 2: Additional fieldbus profiles for real-time networks based on ISO/IEC 8802-3*

IEC 61804 (all parts), *Devices and integration in enterprise systems – Function blocks (FB) for process control and Electronic Device Description Language (EDDL)*

IEC 62541-6, *OPC Unified Architecture – Part 6: Mappings*

IEC 62541-100, *OPC unified architecture – Part 100: Device Interface*

IEC 62769-2, *Field device integration (FDI®) – Part 2: Client*

IEC 62769-3, *Field device integration (FDI®) – Part 3: Server*

IEC 62769-4, *Field device integration (FDI®) – Part 4: FDI® Packages*

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IEC 62769-6, *Field device integration (FDI®) – Part 6: Technology Mapping*

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